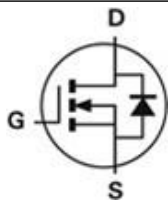


Features

- ◆ 30V, 75A, $R_{DS(ON)}(Typ.) = 3.6m\Omega @ V_{GS} = 10V$.
- ◆ Reliable and Rugged
- ◆ Fast Switching Speed
- ◆ Green Device Available
- ◆ 100% EAS Guaranteed

Application

- ◆ Networking Switch
- ◆ DC/DC Converter

PDFN-5x6 (TOP view)	Symbol
	

Absolute Maximum Ratings $T_A = 25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Unit
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 20	
I_D	Drain Current-Continuous, $T_C = 25^\circ C$	75	A
	Drain Current-Continuous, $T_C = 100^\circ C$	48	
I_{DM}	Drain Current-Pulsed ^a	150	
E_{AS}	Avalanche Energy, Single pulse ^b	51.2	mJ
I_{AS}	Avalanche Current	32	A
P_D	Total Power Dissipation @ $T_C = 25^\circ C$	66	W
	Total Power Dissipation @ $T_C = 100^\circ C$	27	
T_J	Maximum Junction Temperature	150	$^\circ C$
T_{STG}	Junction and Storage Temperature Range	-55 to 150	$^\circ C$

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JC}$	Thermal Resistance Junction-Case	1.88	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ^c	54	$^\circ C/W$

Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

■ Off Characteristics

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	30	-	-	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	$I_D = 1mA$	-	14	-	mV/ $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24V, V_{GS} = 0V$	-	-	1	μA
		$T_J = 55^\circ\text{C}$	-	-	5	
I_{GSS}	Forward Gate Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	± 100	nA

■ On Characteristics

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.2	1.9	2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		-	-5.6	-	mV/ $^\circ\text{C}$
$R_{DS(on)}$	Static Drain-Source On-Resistance ^d	$V_{GS} = 10V, I_D = 30A$	-	3.6	4.6	m Ω
		$V_{GS} = 4.5V, I_D = 15A$	-	5.8	7.5	
gfs	Forward Transconductance	$V_{DS} = 5V, I_D = 15A$	-	49	-	S

■ Dynamic Characteristics

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
R_g	Gate Resistance	$f = 1.0MHz$	-	1.5	-	Ω
C_{iss}	Input Capacitance	$V_{DS} = 15V, V_{GS} = 0V, f = 1.0MHz$	-	996	-	pF
C_{oss}	Output Capacitance		-	335	-	
C_{rss}	Reverse Transfer Capacitance		-	22	-	
$t_{d(on)}$	Turn-On Delay Time	$V_{DS} = 15V, I_D = 15A, R_G = 3.3\Omega, V_{GS} = 10V$	-	4.7	-	ns
t_r	Turn-On Rise Time		-	25	-	
$t_{d(off)}$	Turn-Off Delay Time		-	19	-	
t_f	Turn-Off Fall Time		-	7.5	-	
Q_g	Total Gate Charge	$V_{DS} = 15V, I_D = 15A, V_{GS} = 10V$	-	15.5	-	nC
Q_g	Total Gate Charge	$V_{DS} = 15V, I_D = 15A, V_{GS} = 4.5V$	-	7.6	-	
Q_{gs}	Gate-Source Charge		-	3.1	-	
Q_{gd}	Gate-Drain Charge		-	2.9	-	

■ **Drain-Source Diode Characteristics**

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	$V_G = V_D = 0V$, Force Current	-	-	75	A
I_{SM}	Pulse Source Current		-	-	150	A
V_{SD}	Drain-Source Diode Forward Voltage ^d	$V_{GS} = 0V, I_{SD} = 1A$	-	-	1.2	V
t_{rr}	Reverse Recovery Time	$I_F = 15A, V_{GS} = 0V$ $di/dt = 100A/\mu s$,	-	16	-	ns
Q_{rr}	Reverse Recovery Charge		-	3	-	nC

Notes:

- a: Max. current is limited by junction temperature.
- b: The EAS data shows Max. Rating. The test condition is $V_{DD} = 50V, V_{GS} = 10V, L = 0.1mH, I_{AS} = 32A$.
- c: Surface Mounted on 1in2 FR-4 board with 1oz.
- d: Pulse test (pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$).

■ Typical Characteristics

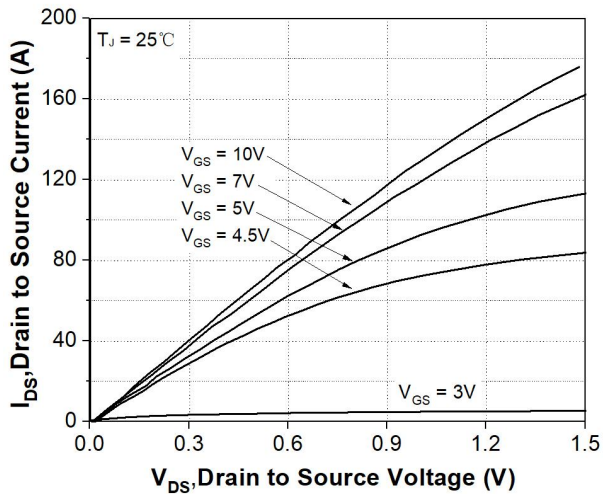


Figure 1. Typical Output Characteristics

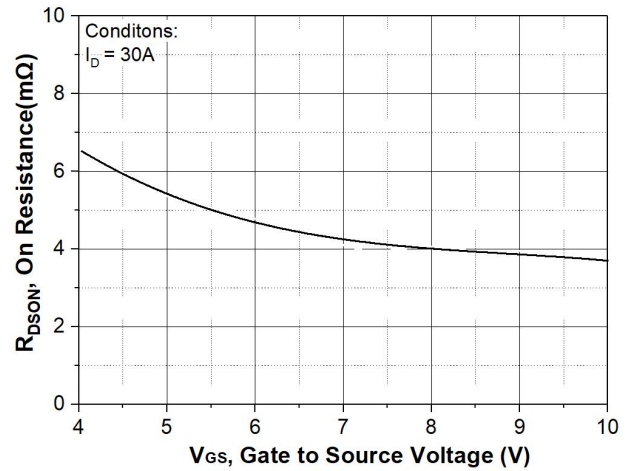


Figure 2. On-Resistance vs. Gate -Source

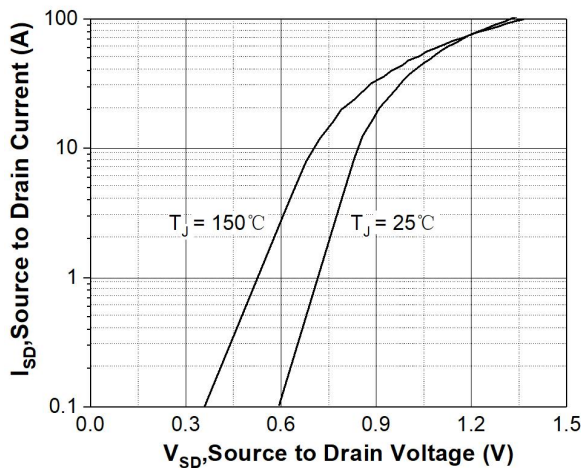


Figure 3. Forward Characteristics of Reverse

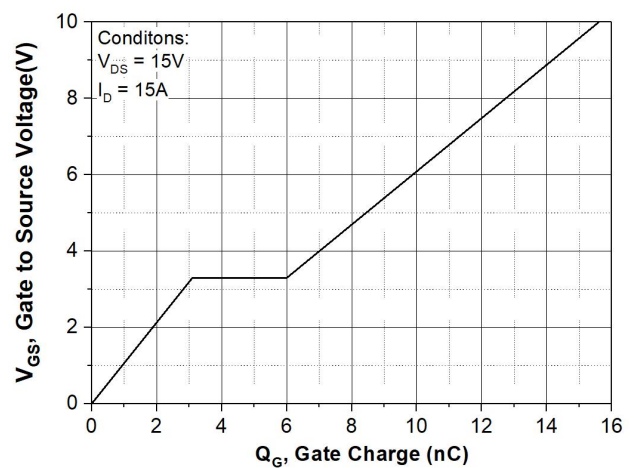


Figure 4. Gate-Charge Characteristics

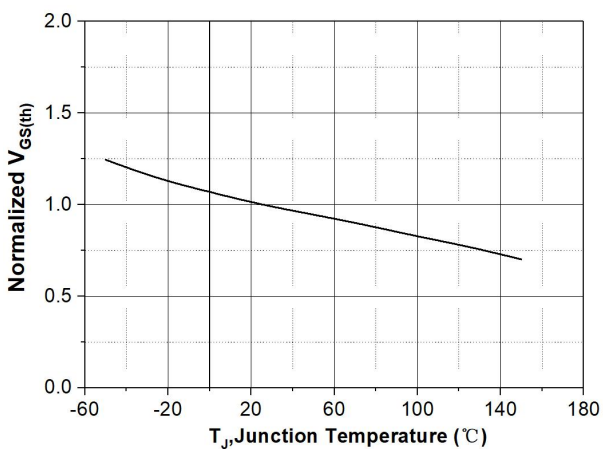


Figure 5. Normalized $V_{GS(th)}$ vs. T_J

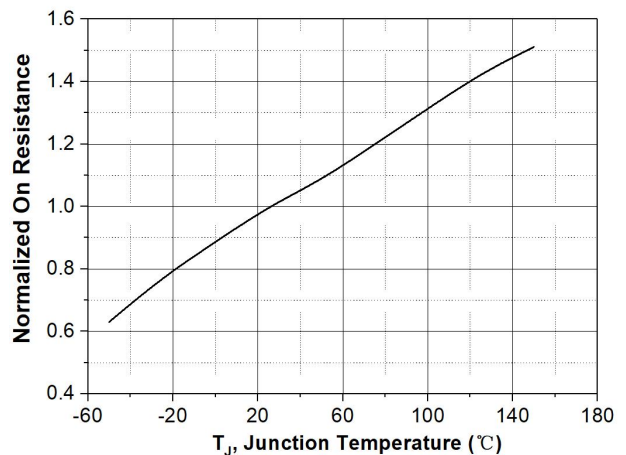


Figure 6. Normalized $R_{DS(on)}$ vs. T_J

■ Typical Characteristics

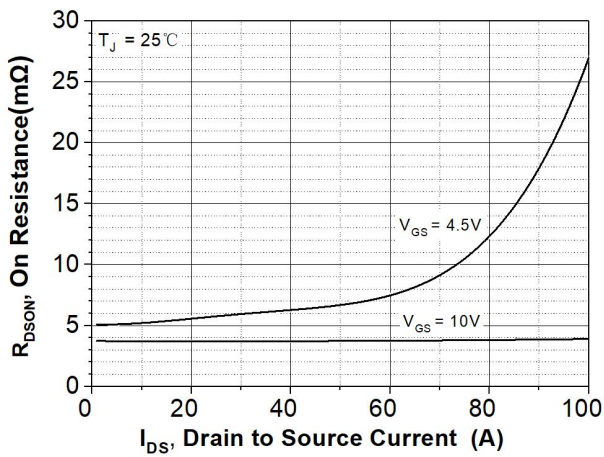


Figure 7. Drain-Source On-State Resistance

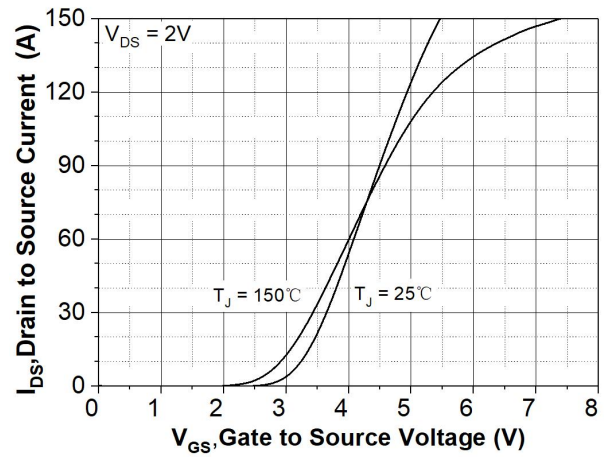


Figure 8. Transfer Characteristics

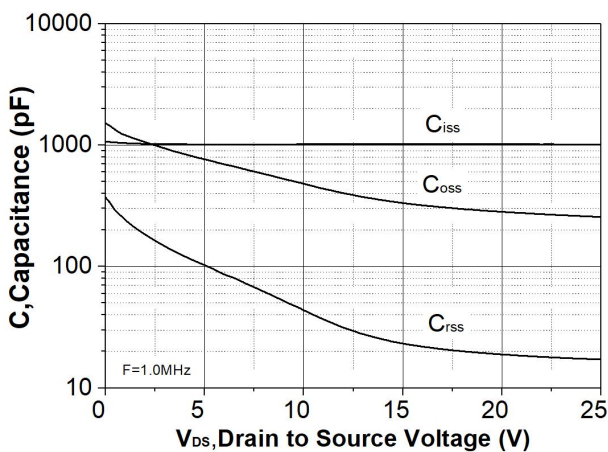


Figure 9. Capacitance

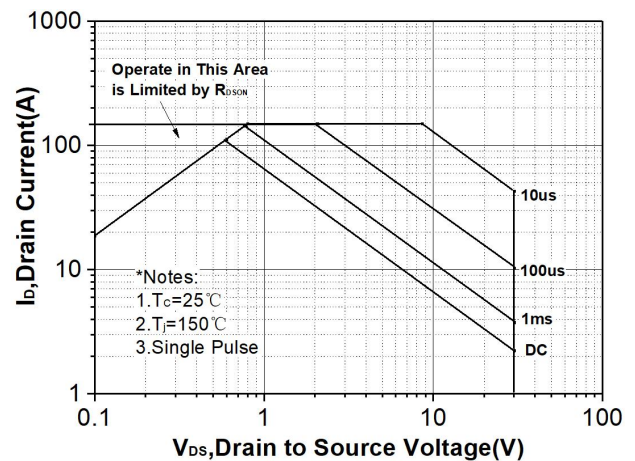


Figure 10. Safe Operating Area

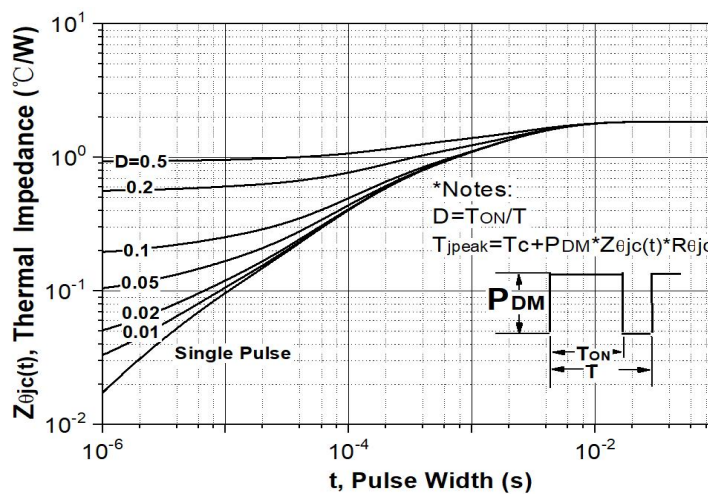


Figure 11. Transient Thermal Impedance

■ Package Information

